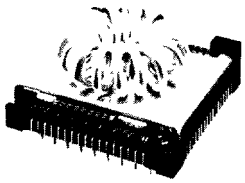
redpoint

CHIPSINKS
C Series – Heatsinks for VLSI (patents pending)



CHIPSINK CT68
MOUNTED IN
TEXTOOL/3M SOCKET

Features
- Suitable for sockets or chip carrier packages.
- High thermal performance.
- Omnidirection orientation.
- Low height.

Description

The Redpoint C series aluminium heatsinks (Chipsinks) provide a compact solution for cooling VLSI mounted in Jedec A&D leadless chip carrier packages, leaded quad packages and in most leadless chip carrier sockets.

The Chipsink toroidal heat exchange surface provides low thermal resistance (θ) performance in mild forced convection, as deployed in compact electronic equipment, by creating high air turbulance but with little hindrance to airflow.

Chipsinks are equally effective when mounted horizontally or vertically and are largely unaffected by airflow direction. The basic design concept is extendable to any pin density.

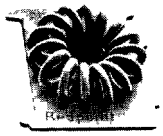
For Jedec A&D leadless chip carriers and leaded quad packages a type CP plain base Chipsink is available. Type CP Chipsinks are normally attached by a recommended cyanoacrylate or epoxy adhesive.

For proprietory LCC sockets incorporating a heatsink lid it is intended that where possible the Chipsink offers a direct substitution for the lid and is retained by the socket clamping arrangement provided. Adhesives are not necessary.

TYPE CP68

A plain base, 18mm square, Chipsink suitable for Jedec A&D 68 and 132 pin LCC packages or 68 leaded quad packages. Adhesive required.

CP68

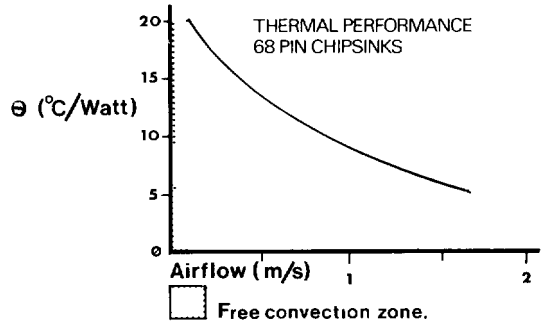


CT68

TYPE CT68

A Chipsink for the Textool/3M 68 pin chip carrier socket (No. 268-5400-00) directly replacing the socket heatsink lid. The Chipsink plate has the same footprint as the socket heatsink lid. No adhesives necessary.

Thermal Performance. Types CP68 and CT68.
9.3°C/W in 1.4 m/s airflow
Height including base plate 9.3mm
Finish – Matt black paint is standard
– Gold and other colours available.



ORDERING INFORMATION (JANUARY 1984)

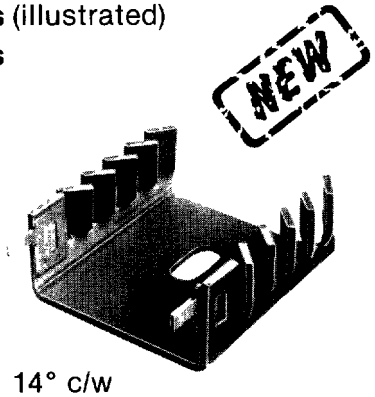
Chipsinks available from stock: CP68, CT68

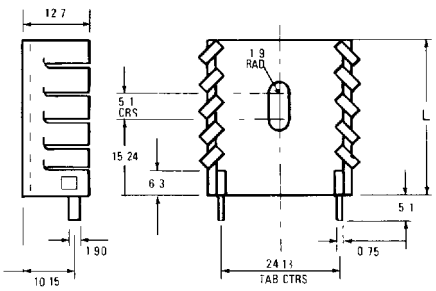
To Order: CP Series – Types CP52, CP44, CP28/24

Available shortly: Versions for other LCC sockets.

Footnote: The same coil design concept is applied to a range of Redpoint Dipsinks for 40 and 64 pin DIPS offering similar features.

TV215 Powerfin with solderable tabs (illustrated)
TV265 Powerfin with solderable tabs





Provides ability to flow solder heatsink to P.C.B.

The design features rugged stake-on solderable tabs.

Mounting slot suitable for wide range of devices.
TO126, TO220, etc.

TV215 'L' = 30.2 Thermal rating θ = 14° c/w
TV265 'L' = 45.0 Thermal rating θ = 12.3° c/w

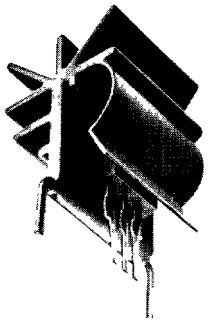
Finish: Black anodised body with solder coated tabs.

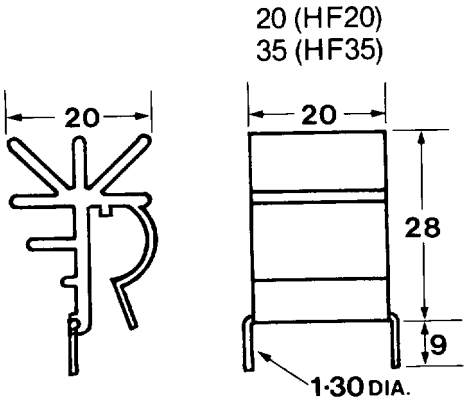
HF - Series Heatsink Clips

Versatile and powerful extruded clip heatsink for TO 126, TO 202, TO 220 and TO 218 devices. Incorporates tinned wire leads for soldering into P.C.B.

HF 20 (Illustrated)
Thermal rating: 13.3°C/W

HF 35
Thermal rating: 11°C/W





Finish: Black anodised with tinned wire leads.

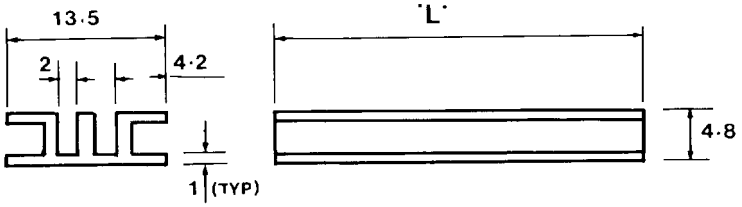
HF 20 at 20 mm length and HF 35 at 35 mm length are standard. Other lengths can be manufactured on request to suit multi device mounting and for SOT 1318, SOT 141 and TDA 1037 packages.

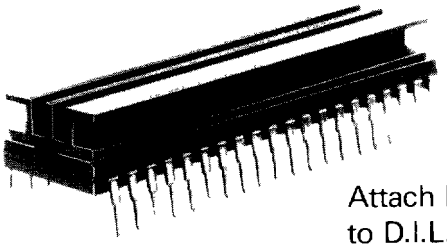
New Dipsink pattern

DIP 1495 series

Low profile - less than 5 mm.
Heatsinks for 24, 28, 40, 48 and 64 pin D.I.L. integrated circuit packages.
The flat top fins allow for device labelling and the section provides excellent thermal performance almost regardless of orientation.

Pattern No.	Length	Device	θ°C/W
DIP 1495	30.5	24 pin	25
DIP 1496	36.6	28 pin	23
DIP 1497	50.8	40 pin	20
DIP 1498	61.0	48 pin	18
DIP 1499	81.3	64 pin	17





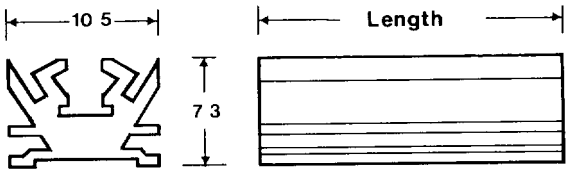
Attach by adhesive to D.I.L. package before or after board assembly.

Finish: Black anodised. All dimensions in mm.

New length versions of 'DIP 1490' profile

Bond-on heatsinks for 8 pin and 20 pin D.I.L. packages

Pattern No.	Length	Device	θ C/W
DIP 1488	25.0	20 pin	29
DIP 1489	10 0	8 pin	70

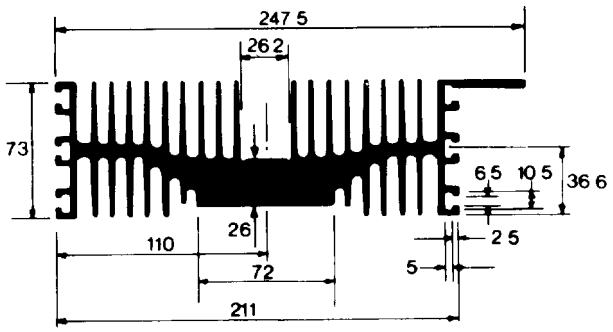


Finish: Black anodised.

Z-Type Powersink

A versatile heatsink for pressure mounted, stud mounted and other semi conductor devices. The heatsink features multiple bolt slots and a flange for fixing and adaption purposes. Custom machining for this and other Redpoint heatsinks available on request. Stock lengths as below. Other lengths available.

Model	Length(mm)	θ°C/W
6Z-1	152 4	54
8Z-1	203 2	47
10Z-1	254 0	44
12Z-1	304 8	42



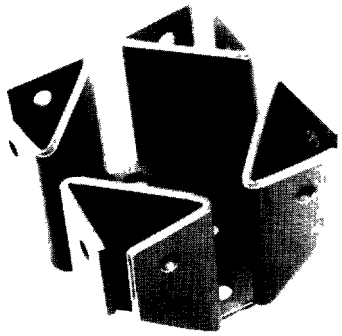
Finish: Black anodised. Alternative conductive phosphate finishes available.

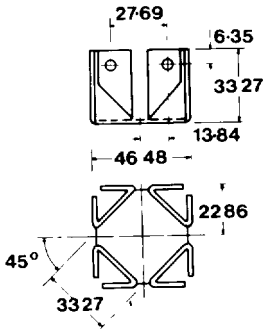
High Power Dissipation Heatsinks

PF 690 Series

Finish: Black anodised.
Thermal rating: 5°C/W

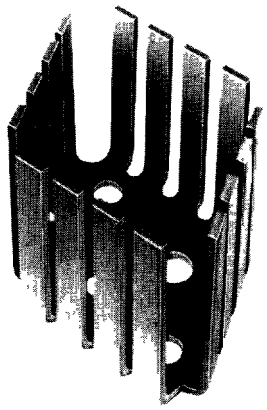
PF 690 for TO3
PF 691 for TO3 (4 pin)
PF 692 for 2 x TO220

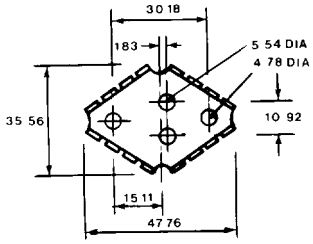




PFO13 Series

Efficient space saving heatsinks in tight situations for TO3 devices.





Model	Dim'A'(mm)	θ°C/W
PFO13	12·7	9
PFO15	25·4	5·2
PFO16	31·75	4·8

Finish: Black anodised.

PF745

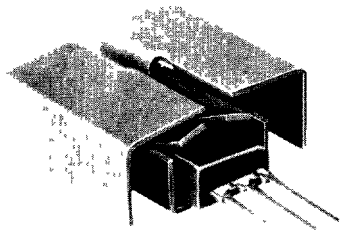
Low cost clip-on heatsink for TO220 devices

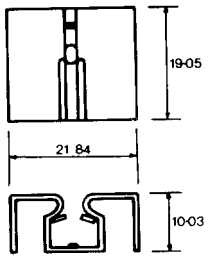
Easy to use – simply insert the TO220 package into the clip as far as the dimple. The device is then retained with pressure applied directly above the device junction providing optimum case to heatsink thermal transfer.

Effective in either horizontal or vertical position. Horizontal is normal.

Thermal rating: 23.3° c/w

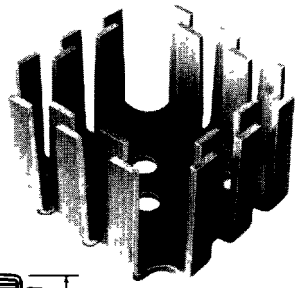
Finish: Black anodised.

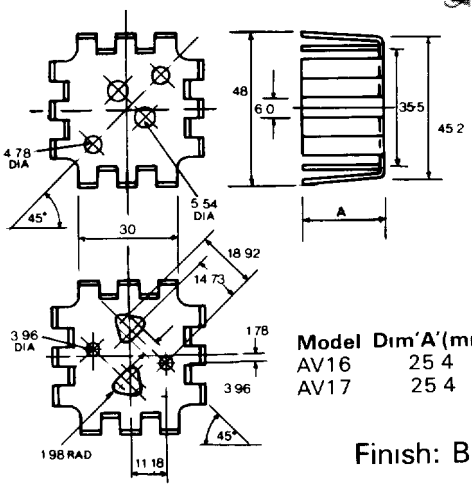




A.V. Series

4 sided heatsink with alternate sloping vanes designed for maximum retained dissipation surface and low unit cost.

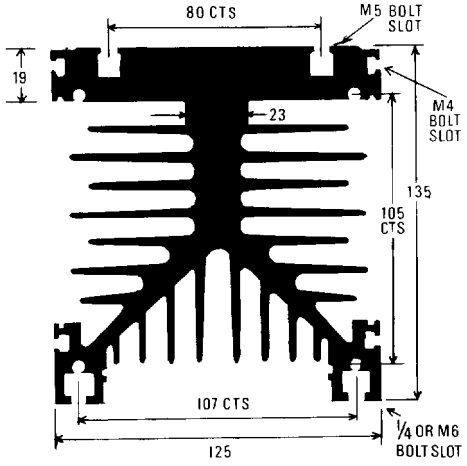




Model	Dim'A'(mm)	Holes	θ°C/W
AV16	25·4	TO3	5·8
AV17	25·4	TO220	5·8

Finish: Black anodised.

D Type Powersink



Pattern No.	Length ins	Length mm	Thermal rating θ°C/W
4D-1	4	101.6	0.51
6D-1	6	152.4	0.37
9D-1	9	228.6	0.27

Features extruded tee-slots for mounting 80mm power modules and solid state relays. Stud devices may also be mounted.

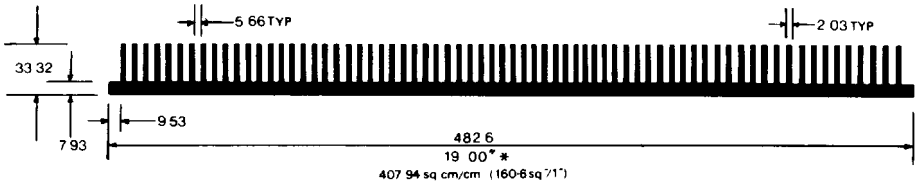
Cover slides on 3 sides may be easily provided. Top surface is machined flat.

23mm stem can be drilled and tapped for stud devices up to M20. For fan cooled units using the D Type – see 400 Series.

Finish: Black anodised.

EC-Type Powersink

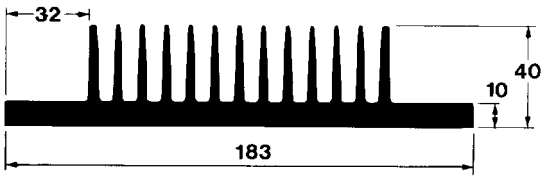
At 19 inches in width, this single-sided heatsink finds ready application within standard racking and case systems. It is available cut to custom length and with the choice of black anodised or conductive phosphate finishes. Any hole complement is readily available.



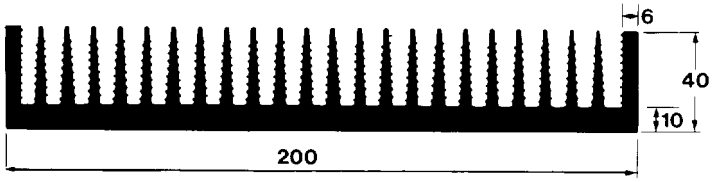
Model	Length(mm)	Finish	θ°C/W
3EC-1	76 2	Black anodised	0 51
3EC-1PH	76 2	Conductive phosphate	
3EC-1BRT	76 2	Raw aluminium	

*Width matches panels to I.E.C. (2nd ed.), and DIN41494.

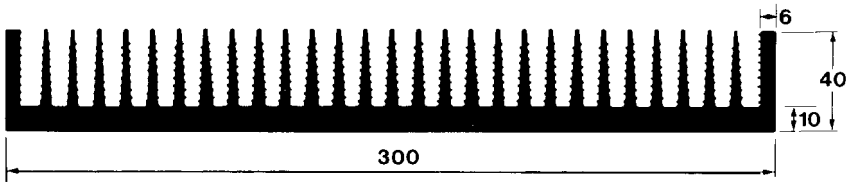
ED Powersink



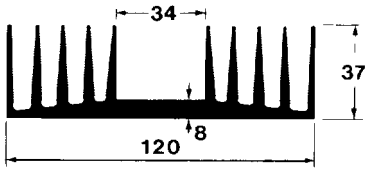
EE Powersink



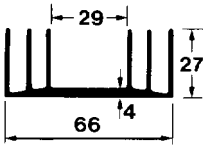
EF Powersink



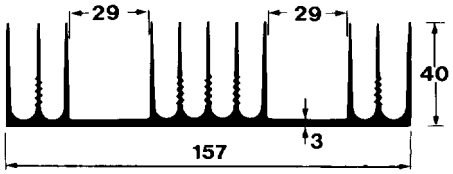
MD Powersink



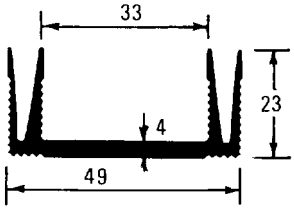
ME Powersink



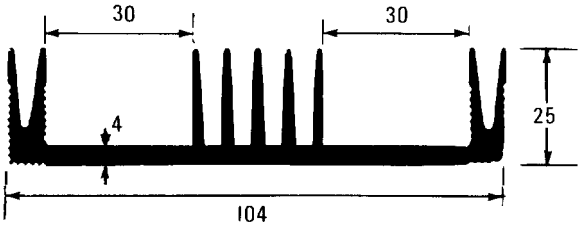
MG Powersink



MH Powersink



MJ Powersink



Pattern No	Length ins	Length mm	Thermal Rating θ° c/w
3ED-1	3	76.2	1.41
6ED-1	6	152.4	1.00
9ED-1	9	228.6	0.74
3EE-1	3	76.2	0.65
4EE-1	4	101.6	0.50
6EE-1	6	152.4	0.38
9EE-1	9	228 6	0.33
3EF-1	3	76.2	0.44
4EF-1	4	101.6	0 40
6EF-1	6	152.4	0 34
9EF-1	9	228 6	0 28

Pattern No.	Length ins	Length mm	Thermal Rating θ° c/w
2MD-1	2	50.8	1 97
3MD-1	3	76.2	1 40
4MD-1	4	101.6	1.18
5MD-1	5	127 0	1 05
6MD-1	6	152 4	0 93
2ME-1	2	50.8	3.3
3ME-1	3	76.2	2.8
4ME-1	4	101 6	2.3
6ME-1	6	152 4	1.8
3MG-1	3	76 2	1.25
6MG-1	6	152.4	0.64
9MG-1	9	228 6	0.40
2MH-1	2	50 8	4.9
4MH-1	4	101 6	3.2
6MH-1	6	152.4	2.4
2MJ-1	2	50 8	2.9
4MJ-1	4	101 6	1 9
6MJ-1	6	152.4	1 3

Finish: Black anodised.
Other lengths available to order.

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